

**KBJ6005G THRU KBJ610G
GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER**

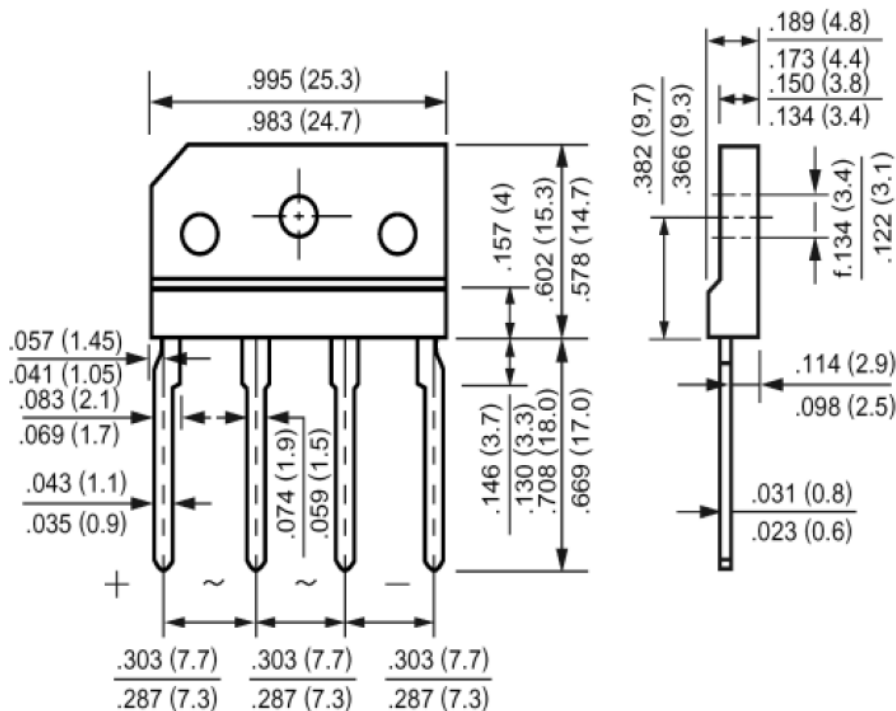
Features:

- Glass passivated chip junction KBJ
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low forward voltage drop
- Low reverse leakage current
- High surge current capability

Mechanical Data:

- Case: Molded plastic, KBJ
- Epoxy: UL 94V-O rate flame retardant
- Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed
- Mounting position: Any
- Weight: 0.16ounce, 4.6gram

Mechanical Dimensions: In Inches/mm



KBJ

MARKING, MOLDING RESIN

Marking for Type Number, 1st row SSG YYWWL, 2nd row Type Number
Where YY is the manufacture year
WW is the manufacture week code
L is the wafer's Lot Number

- China - Germany - Korea - Singapore - United States •
- <http://www.smc-diodes.com> - sales@smc-diodes.com •



KBJ6005G THRU KBJ610G

Technical Data
Data Sheet N1819, Rev. -

Green Products

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Maximum Ratings:

Type Number	Symbol	KBJ 6005G	KBJ 601G	KBJ 602G	KBJ 604G	KBJ 606G	KBJ 608G	KBJ 610G	Unit
Maximum Recurrent Peak Reverse Voltage Maximum DC Blocking Voltage	V_{RRM} V_{DC}	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum Average Forward Rectified Current @ $T_C = 110^\circ\text{C}$	$I_{(AV)}$	6.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	150							A

Electrical Characteristics:

Type Number	Symbol	KBJ 6005G	KBJ 601G	KBJ 602G	KBJ 604G	KBJ 606G	KBJ 608G	KBJ 610G	Unit
Maximum Forward Voltage @ $I_F = 3.0\text{A}$	V_{FM}	1.0							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_R	5.0 500							μA
Typical Junction Capacitance (Note 1)	C_J	80							pF

Thermal-Mechanical Specifications:

Type Number	Symbol	KBJ 6005G	KBJ 601G	KBJ 602G	KBJ 604G	KBJ 606G	KBJ 608G	KBJ 610G	Unit
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	1.5							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$
Case Style		KBJ							

Note: 1. Measured at 1 MHz and applied reverse voltage of 4.0 VDC.

2. Thermal Resistance from Junction to Case with Device Mounted on 75mm x 75mm x 1.6mmC u Plate Heatsink.

-
- China - Germany - Korea - Singapore - United States •
 - <http://www.smc-diodes.com> - sales@smc-diodes.com •

FIG.1- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER BRIDGE ELEMENT

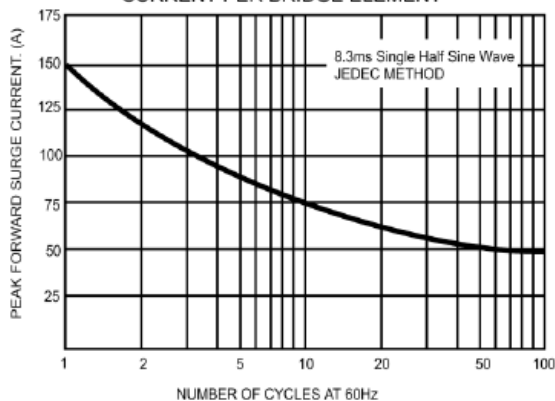


FIG.2- MAXIMUM FORWARD CURRENT DERATING CURVE

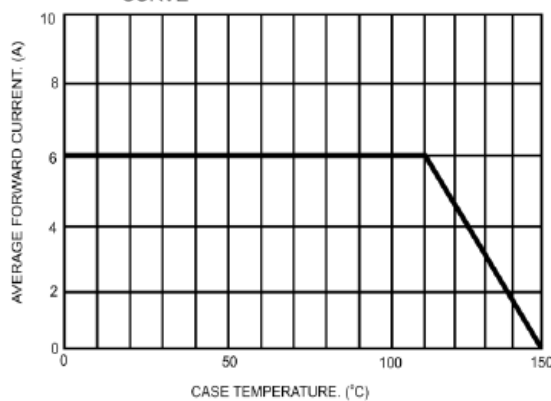


FIG.3- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER BRIDGE ELEMENT

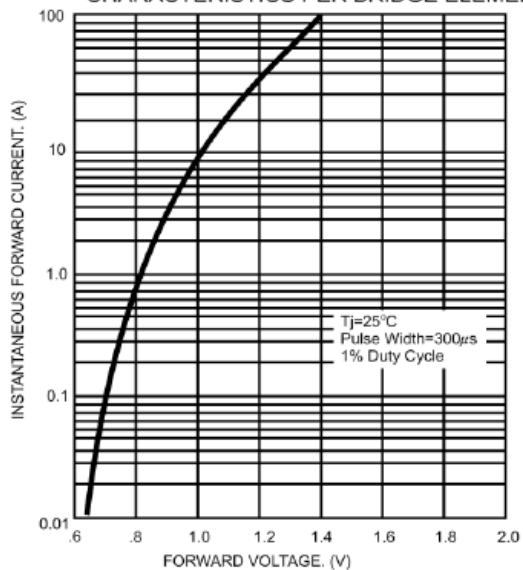
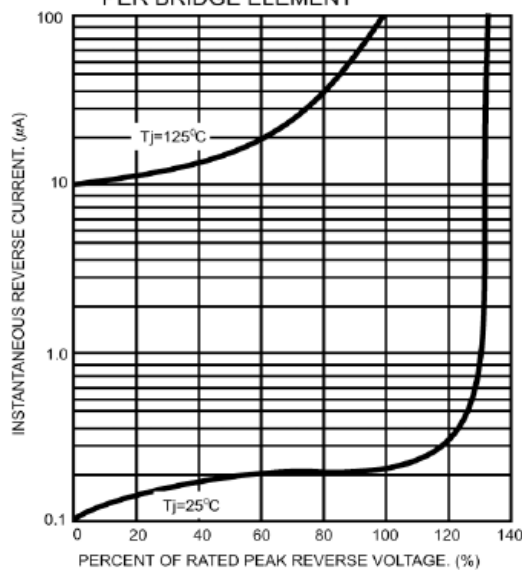


FIG.4- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT





DISCLAIMER:

- 1- The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are advised to contact the SMC - Sangdest Microelectronics (Nanjing) Co., Ltd sales department for the latest version of the datasheet(s).
- 2- In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, medical equipment, and safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement.
- 3- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any damages that may result from an accident or any other cause during operation of the user's units according to the datasheet(s). SMC - Sangdest Microelectronics (Nanjing) Co., Ltd assumes no responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in the datasheets.
- 4- In no event shall SMC - Sangdest Microelectronics (Nanjing) Co., Ltd be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.
- 5- No license is granted by the datasheet(s) under any patents or other rights of any third party or SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.
- 6- The datasheet(s) may not be reproduced or duplicated, in any form, in whole or part, without the expressed written permission of SMC - Sangdest Microelectronics (Nanjing) Co., Ltd.
- 7- The products (technologies) described in the datasheet(s) are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety nor are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations..